

K3591-01MR_0-VB Datasheet N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	$DSS(V) \qquad R_{DS(on)}(\Omega)$		Q _g (Typ.)	
200	0.038 at V _{GS} = 15 V	45	57	
	0.043 at V _{GS} = 10 V	40	57	

FEATURES

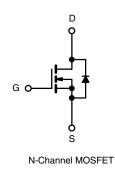
- TrenchFET[®] Power MOSFETS
- 175 °C Junction Temperature
- 100 % R_g and UIS Tested

APPLICATIONS

- Power Supply
- Lighting Systems







ABSOLUTE MAXIMUM RATING	S T _A = 25 °C, unless oth	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	200	V		
Gate-Source Voltage	V _{GS}	± 25	V		
Continuous Drain Current ($T_1 = 175 \ ^{\circ}C$)	T _C = 25 °C	I_	45		
Continuous Drain Current $(1) = 175$ C)	T _C = 100 °C	I _D	26		
Pulsed Drain Current		I _{DM}	150	A	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20	7	
Single Pulse Avalanche Energy ^a	L = 0.1 min	E _{AS}	20	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	Р	55 ^b	W	
	T _A = 25 °C ^c	– P _D	3.12		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)	R _{thJC}	0.75		

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS (T _J = 25 $^{\circ}$	C, unless o	otherwise noted)				
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	200			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50	μA
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 10 V$	40			А
		V _{GS} = 10 V, I _D = 3 A		0.048		- Ω
	R _{DS(on)}	V _{GS} = 10 V, I _D = 3 A, T _J = 125 °C		0.050		
Drain-Source On-State Resistance ^b		V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C		0.070		
		V _{GS} = 6 V, I _D = 3 A		0.092		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		35		S
Dynamic ^a						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		2800		pF
Output Capacitance	C _{oss}			180		
Reverse Transfer Capacitance	C _{rss}			80		
Total Gate Charge ^c	Qg	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 3 A		34	51	nC
Gate-Source Charge ^c	Q _{gs}			8		
Gate-Drain Charge ^c	Q _{gd}			12		
Gate Resistance	R _g		0.5		2.9	Ω
Turn-On Delay Time ^c	t _{d(on)}			15	25	ns
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, \text{ R}_{L} = 5.2 \Omega$ $\text{I}_{D} \cong 3 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{g} = 2.5 \Omega$		50	75	
Turn-Off Delay Time ^c	t _{d(off)}			30	45	
Fall Time ^c	t _f			60	90	
Source-Drain Diode Ratings and Char	acteristics (1	Γ _C = 25 °C)		<u> </u>		
Pulsed Current	I _{SM}				30	A
Diode Forward Voltage ^b	V _{SD}	I _F = 3 A, V _{GS} = 0 V		0.9	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3 A, dl/dt = 100 A/μs		180	250	ns

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

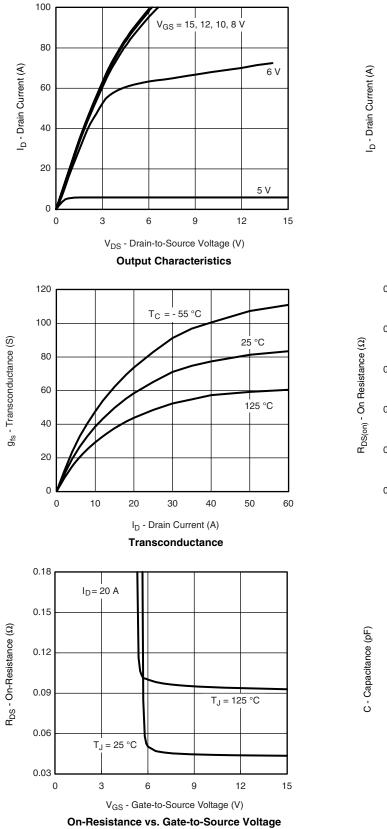
c. Independent of operating temperature.

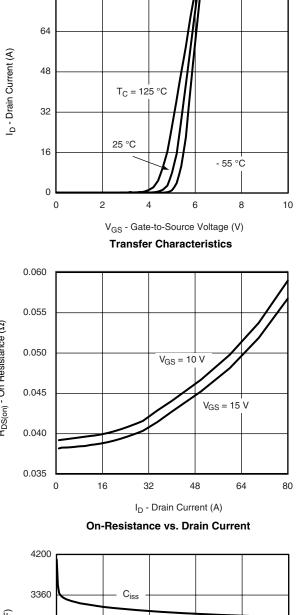
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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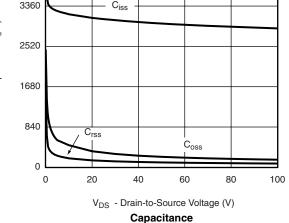


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



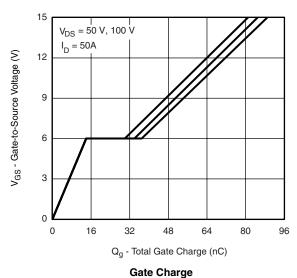


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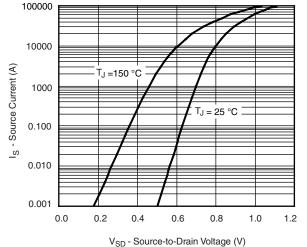


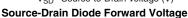


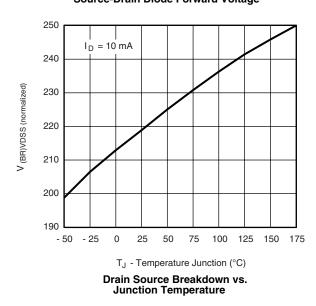
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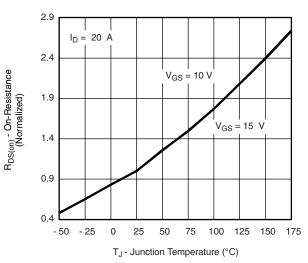




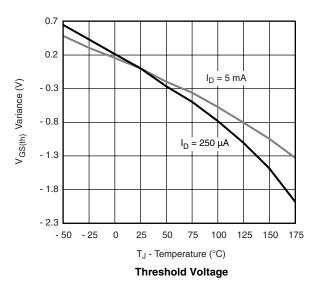


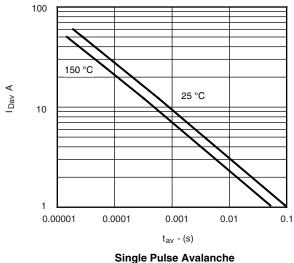


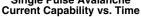




On-Resistance vs. Junction Temperature



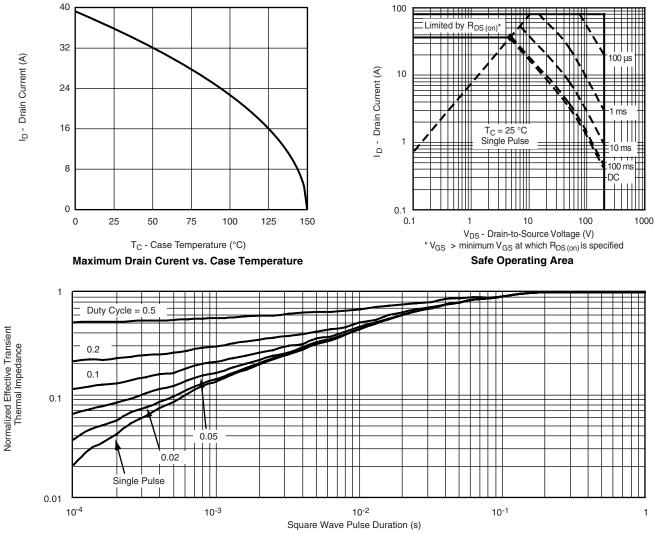




K3591-01MR_0-VB



THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



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